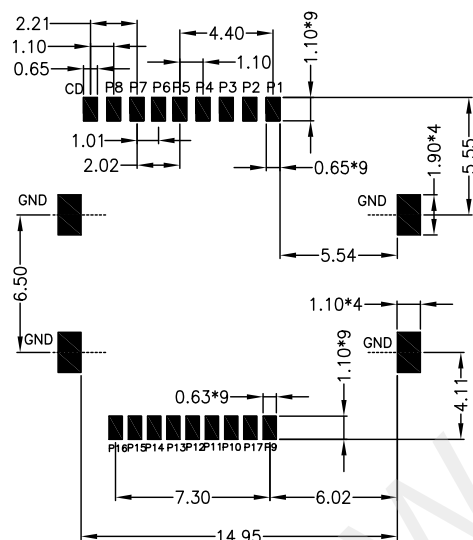
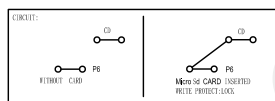
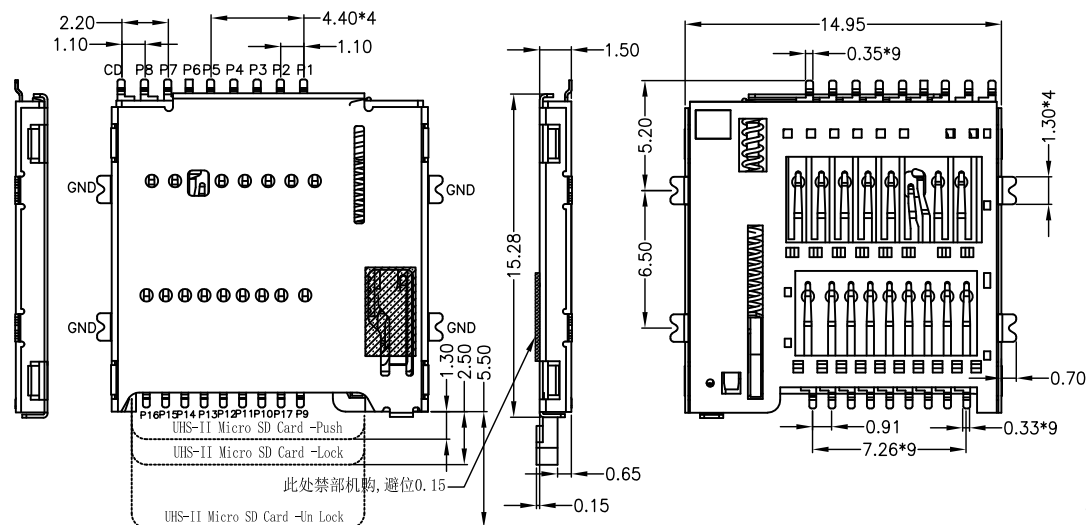


RECOMMEND PCB LAYOUT:  PCB AREA 焊接区
(Unit:mm .X ± 0.15 .XX ± 0.05 .XXX ± 0.02)

PIN NO.	Micro SD With UHS-II and SWIO support
P1	DAT2 (Data Line Bit 2)
P2	CD/DAT3 (card Detect/Data Line)
P3	CMD (Command/Response)
P4	VDD1 (Supply voltage 3.3V)
P5	CLOCK
P6	VSS (Supply voltage ground)
P7	DAT0/RCLK+ (Data Line/RCLK+)
P8	DAT1/RCLK- (Data Line/RCLK-)
P9	CD (检测P)
	GND
	GND
	GND
	GND
P9	Vdd2(supply voltage ground1.8v)
P10	Vss(supply voltage ground)
P11	UHS-II DO+
P12	UHS-II DO-
P13	Vss(supply voltage ground)
P14	UHS-II DI-
P15	UHS-II DI+
P16	Vss(supply voltage ground)
P17	SWIO (Single wire protocol interface)

MATERIAL:

Specification

Insulator: High Temperature Thermoplastic,
UL 94V-0. COLOR"BLACK LCP

(塑胶: 黑色LCP, 防火等级UL 94V-0)

SHELL: SUS301

Contact: Copper Alloy (磷铜C5210)

弹簧: 琴钢线

拉杆: SUS301

PLATING:

Contact:All Ni50u,contact area 1u Au,Pad 0.8U Au

(接触端子电镀: 全部镍底50U, 接触区域1U金, 焊脚处0.8U金最少)

Shell:All 50u Ni,Pad 0.8 Au

(外壳电镀: 镍底50U, 焊接处0.8U金)

Electrical:

Current Rating :0.5Amps max(额定电流:0.5A最大)

Voltage Rating :5V AC/DC(额定电压:5V AC/DC)

Ambient Temperature Range :-40° C~+80° C(工作温度: -40度到+85度)

Storage Temperature Range :-40° C~+80° C (工作环境: -40度到+85度)

Ambient Humidity Range :95% R.H. Max. (上锡效果: 95%以上)

Contact Resistance:100mΩmax. (端子接触电阻: 100mΩ最大)

Insulation Resistance:1000MΩmin./500VDC(绝缘阻抗: 100兆欧最小)

Mating Cycles:1500 Insertions (寿命: 1500次)

产品耐温温度: 260° C



深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X' ±2" X.X' ±0.5"	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: TF PUSH 4.0卡座 1.5H 全贴
UNIT: mm [inch] SCALE:1:1 SIZE: A4	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYC149-TF18-150
	APPROVED BY: 邱敏	DATE : 2014-02-23	MOLD NO. DRAW NO: HYC-2211251559
			SHEET NO. 1 OF 1